

## **EMA 2019 Confirmed Invited Speakers**

### **S1: Characterization of Structure-Property Relationships in Functional Ceramics**

Dominique Bernard, ICMCB-CNRS, France  
Marco Deluca, Materials Center Leoben, Austria  
David Keen, Rutherford Appleton Laboratory, UK  
Jurij Koruza, Technische Universität Darmstadt, Germany  
Michael Manley, Oak Ridge National Laboratory, USA  
Lane Martin, University of California, Berkeley, USA  
Xiaoli Tan, Iowa State University, USA

### **S2: Advanced Electronic Materials: Processing Structures, Properties, and Applications**

Dragan Damjanovic, EPFL, Switzerland  
Brahim Dkhil, Centrale Supelec, France  
Ichiro Fujii, University of Yamanashi, Japan  
Koichi Hayashi, Nagoya Institute Technology, Japan  
Jacob Jones, NC State University, USA  
Soonil Lee, Changwon University, Korea  
Baowen Li, Wuhan University Technology, China  
Jing-Feng Li, Tsinghua University, China  
Vojislav Mitic, Serbian Academy of Sciences, Serbia  
Zuo-Guang Ye, Simon Fraser University, Canada  
Kui Yao, Institute of Materials Research and Engineering, Singapore  
Jinxing Zhang, Beijing Normal University, China

### **S3: Frontiers in Ferroic Oxides: Synthesis, Structure, Properties, and Applications**

Marco Campanini, EMPA, Switzerland  
Jia-Mian Hu, University of Wisconsin-Madison, USA  
Bhagwati Prasad, University of California, Berkeley, USA  
Jan Seidel, University of New South Wales, Australia  
Srinivasa Rao Singamaneni, University of Texas, El Paso, USA  
Mads Weber, ETH Zurich, Switzerland

### **S4: Complex Oxide Thin Film Materials Discovery: From Synthesis to Strain/Interface Engineered Emergent Properties**

John Ekerdt, University of Texas, Austin, USA  
Roman Engel-Herbert, Pennsylvania State University, USA  
John Freeland, Argonne National Laboratory, USA  
Arthur Hebard, University of Florida, USA  
Megan Holtz, Cornell University, USA  
Divine Kumah, North Carolina State University, USA  
Ho Nyung Lee, Oak Ridge National Laboratory, USA  
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Peter Petrov, Imperial College London, UK  
Guus Rijnders, University of Twente, Netherlands  
Uwe Schroeder, NamLab GmbH, Germany  
Aloysius Soon, Yonsei University, South Korea

### **S5: Mesoscale Phenomena in Ferroic Nanostructures: Beyond the Thin-Film Paradigm**

Aiping Chen, Los Alamos National Laboratory, USA  
Marty Gregg, Queens University Belfast, UK  
Jiri Hlinka, Czech Academy of Sciences, Czech Republic  
Ho Nyung Lee, Oak Ridge National Laboratory, USA  
Patrycja Paruch, University of Geneva, Switzerland  
Margo Staruch, Naval Research Laboratory, USA

### **S6: Complex Oxide and Chalcogenide Semiconductors: Research and Applications**

Cyrus Dreyer, Stony Brook University, USA  
Vincent Garcia, CRNS-Thales, France  
Bharat Jalan, University of Minnesota, USA  
Robert Klie, University of Illinois at Chicago, USA  
James LeBeau, Massachusetts Institute of Technology, USA  
Matthew McCluskey, Washington State University, USA  
Katrina Morgan, University of Southampton, UK  
Seongshik Oh, Rutgers University, USA  
Jayakanth Ravichandran, University of Southern California, USA  
Paul Rogge, Drexel University, USA

### **S7: Superconducting and Magnetic Materials: From Basic Science to Applications**

Thomas Bullard, Air Force Research Laboratory, USA  
Riccardo Comin, Massachusetts Institute of Technology, USA  
Xiaoli Dong, Institute of Physics, CAS, China  
Timothy Haugan, Air Force Research Laboratory, USA  
Ian Fisher, Stanford University, USA  
Jennifer Hoffman, Harvard University, USA  
Jijie Huang, Purdue University, USA  
Jinfeng Jia, Shanghai Jiao Tong University, China  
Peng Jiang, Chinese Academy of Sciences, China  
Richard Klemm, University of Central Florida, USA  
Katjana Lange, University of Cambridge, UK  
Kai Liu, Georgetown University, USA  
Xucun Ma, Tsinghua University, China  
Sheng Ran, University of Maryland, USA  
Keith Taddei, Oak Ridge National Laboratory, USA  
Zafer Turgut, Air Force Research Laboratory, USA

Wenhong Wang, Institute of Physics, CAS, China

Judy Wu, University of Kansas, USA

Yanwu Xie, Stanford University, USA

Xiaodong Xu, University of Washington, USA

Ding Zhang, Tsinghua University, China

Fan Zhang, University of Texas at Dallas, USA

Xingjiang Zhou, Chinese Academy of Sciences, China

#### **S8: Structure-property Relationships in Relaxor Ceramics**

Danila Amoroso, University of Liege, Belgium

Elena Buixaderas, Czech Academy of Sciences, Czech Republic

Michelle Dolgos, Oregon State University, USA

Igor Levin, NIST, USA

Finlay Morrison, University of St. Andrews, UK

Andrew M. Rappe, University of Pennsylvania, USA

Tadej Rojac, Institute Jozef Stefan, Slovenia

Dwight Viehland, Virginia Tech, USA

Dawei Wang, University of Sheffield, UK

Thomas R. Welberry, Australian National University, Australia

#### **S9: Ion Conducting Ceramics**

Yan-Yan Hu, Florida State University, USA

Cheng Ge, Institute of Physics, CAS, China

Judith MacManus-Driscoll, University of Cambridge, UK

Yue Qi, Michigan State University, USA

Shriram Ramanathan, Purdue University, USA

Eric Stach, University of Pennsylvania, USA

Maria Sushko, Pacific Northwest National Laboratory, USA

Hua Zhou, Argonne National Laboratory, USA

#### **S10: Current Challenges in Microstructural Evolution: From Basic Science to Electronic Applications**

David Diercks, Colorado School of Mines, USA

Yanhao Dong, Massachusetts Institute of Technology, USA

Hui Gu, Shanghai University, China

Yuichi Ikuhara, University of Tokyo, Japan

Mehmet Gulgur, Sabanci Universiti, Turkey

Amanda Krause, Lehigh University, USA

Jiangyu Li, University of Washington, USA

Paul Meredith, Swansea University, UK

Hadas Sternlicht, Brown University, USA

#### **S11: Electronic Materials Applications in 5G Telecommunications**

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Jasper Drisko, National Institute of Standards and Technology, USA  
Songbin Gong, University of Illinois, USA  
Matthew Hardy, U.S. Naval Research Laboratory, USA  
Michael Hill, Skyworks, Inc. USA  
Guru Khalsa, Cornell University, USA  
Nathan Newman, Arizona State University, USA  
Christopher Nordquist, Sandia National Laboratories, USA

**S12: Thermal Transport in Functional Materials and Devices**

Lucas Lindsay, Oak Ridge National Laboratory, USA  
Jonathan Malen, Carnegie Mellon University, USA

**S13: From Basic Science to Agile Design of Functional Materials: Aligned Computational and Experimental Approaches and Materials Informatics**

Rohit Batra, Georgia Tech, USA  
Letian Dou, Purdue University, USA  
Richard Hennig, University of Florida, USA  
Sergey Levchenko, Skolkovo Institute of Science & Technology, Russian Federation  
Yuanyue Liu, University of Texas at Austin, USA  
Dane Morgan, University of Wisconsin-Madison, USA  
Andrew Rappe, University of Pennsylvania, USA  
Qiang Zhang, Louisiana State University, USA